MICROCHIP Semiconductor Device Type: AUA 004 VLGA 2.5x2.0x0.89mm NiAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				J-STD-609A Product Marking and/or Pkg. Labeling e3
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	malaart		4.37	(mg) Total	Mold Compound	% ot Total Weight	59.00
Silica(Amorphous) A	60676-86-0	Mold Compound	44.427	mg/part 3.288	ppm 444,270		Silica(Amorphous) A	60676-86-0	75.30	i -
Silica(Amorphous) B	7631-86-9	Mold Compound	5.924	0.438	59,236		Silica(Amorphous) B	7631-86-9	10.04	
Epoxy Resin	Trade Secret	Mold Compound	4.773	0.353	47,731		Epoxy Resin	Trade Secret	8.09	
Phenol Resin	9003-35-4	Mold Compound	1.776	0.131	17,759		Phenol Resin	9003-35-4	3.01	
Aluminium and its compounds	Trade Secret	Mold Compound	1.776	0.131	17,759		Aluminium and its compounds	Trade Secret	3.01	
Carbon Black	1333-86-4	Mold Compound	0.325	0.024	3,245		Carbon Black	1333-86-4	0.55	
Copper	7440-50-8	Lead Frame	7.018	0.519	70,185			Total	100.00	
Glass fibers	65997-17-3	Lead Frame	4.184	0.310	41,837	1.45	(mg) Total	Lead Frame	% of Total Weight	19.55
Phenol, polymer	9003-36-5 7631-86-9	Lead Frame	4.184	0.310	41,837		Copper Glass fibers	7440-50-8 65997-17-3	35.90	
Silica, chemically prepared Nickel	7631-86-9	Lead Frame	0.762	0.116	15,640 7.625		Phenol, polymer	9003-36-5	21.40	
Barite	7727-43-7	Lead Frame	0.489	0.036	4,888		Silica, chemically prepared	7631-86-9	8.00	
Magnesium silicate	14807-96-6	Lead Frame	0.391	0.029	3,910		Nickel	7440-02-0	3.90	
Araldite GY 250	25068-38-6	Lead Frame	0.391	0.029	3,910		Barite	7727-43-7	2.50	
(2-Methoxymethylethoxy)propanol	34590-94-8	Lead Frame	0.156	0.012	1,564		Magnesium silicate	14807-96-6	2.00	1
Misc.	system	Lead Frame	0.293	0.022	2,933		Araldite GY 250	25068-38-6	2.00	
Aluminium-hydroxide-oxide	24623-77-6	Lead Frame	0.098	0.007	978		(2-Methoxymethylethoxy)propanol	34590-94-8	0.80	
Gold	7440-57-5	Lead Frame	0.020	0.001	196		Misc.	system	1.50	
Silver	7440-22-4	Die Attach 1	0.675	0.050	6,750		Aluminium-hydroxide-oxide	24623-77-6	0.50	
Epoxy Resin	Trade secret	Die Attach 1	0.075	0.006	750		Gold	7440-57-5 Total	0.10	J
SiO2 Filler	Trade Secret	Die Attach 2	0.772	0.057	7,723			10101		0.75
Epoxy Resin Acrylic Copolymer	Trade Secret Trade Secret	Die Attach 2 Die Attach 2	0.390	0.029	3,899 2,339	0.06	(mg) Total Silver	Die Attach 1 7440-22-4	% of Total Weight 90.00	0.75
Phenol Resin		Die Attach 2 Die Attach 2	0.234	0.017	2,339		Epoxy Resin	Trade secret	10.00	
Doped Silicon	Trade Secret 7440-21-3	Chip (Die) 1	3.810	0.282	38,100		Epoxy Resin	Total	10.00	l
Doped Silicon	7440-21-3	Chip (Die) 1 Chip (Die) 2	1.700	0.126	17,000	0.12	(mg) Total	Die Attach 2	% of Total Weight	1.63
Doped Gold	7440-21-3	Wire Bond 1	0.650	0.128	6,500	0.12	SiO2 Filler	Trade Secret	47.38	1.63
Doped Gold	7440-57-5	Wire Bond 2	0.150	0.040	1,500		Epoxy Resin	Trade Secret	23.92	
Copper	7440-50-8	Plating on external leads (pins)	12.250	0.906	122,496		Acrylic Copolymer	Trade Secret	14.35	
Ni	7440-02-0	Plating on external leads (pins)	0.383	0.028	3,828		Phenol Resin	Trade Secret	14.35	
Au	7440-57-5	Plating on external leads (pins)	0.128	0.009	1,276		<u>L</u>	Total	100.00	1
		TOT		7.400	1,000,000	0.28	Total (mg)	Chip (Die) 1	% of Total Weight	3.81
		Total Mass	ALS: 100.000	7.400	1,000,000	0.28	Total (mg) Doped Silicon	7440-21-3	% of Total Weight 100.00	3.81
s semiconductor device and its homogenous materials comply with 5) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) with	EU Directives: 200	Total Mass //95/EC (27 January 2003) & Directive 2011/65/EU	ALS: 100.000	7.400	1,000,000	0.28			% of Total Weight	3.81
5) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) with npliance with the above EU Directives has been verified via internal	EU Directives: 200 nout exemption (zero design controls, su	Total Mass 2/95/EC (27 January 2003) & Directive 2011/65/EU) pplier declarations, and /or analytical test data.	ALS: 100.000 (08 June 2011) and	7.400 1 2015/863/EU	1,000,000 31 March	0.28		7440-21-3	% of Total Weight 100.00	3.81
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and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) with ipliance with the above EU Directives has been verified via internal shemical substance is absent from the list above, the chemical sub rporated's knowledge and belief as of the date of this document, it below the threshold of regulatory concern for any regulatory sch ting compounds used by Microchip meet the UL94 V0 flammability //ul.com/global/eng/pages/offerings/Industries/chemicals/plastics/ protective "tubes" in which the specific product is shipped are ma in "reels" may be made from PVC plastic. ochip Technology Incorporated believes the information in this for original packing materials is true and correct to the best of its knn, pleteness and accuracy of data in this form because it has been co mation is often protected from disclosure as trade secrets and so ided only as estimates of the average weight of these parts and th nst, metals, and non-metal materials contained within silicon devi ochip Technology Incorporated does not provide any warranty, ex antios sorder acknowledgement, and invoices. ochip disclaims any duty to notify users of updates or changes to rwise, suffered by users or third parties as a result of the users' re Certificate of Compliance for semiconductor products.	EU Directives: 200 lout exemption (zer design controls, su istance is NOT an ir here is no credible r eme world-wide. standard for plasti de from polyvinyl c rm concerning subs bowledge and belief, ompiled based on the information may e average weight of fices (silicon IC) in ti press or implied, w ssidiaries are conta Material Content De liance on the inform	Total Mass //95/EC (27 January 2003) & Directive 2011/65/EU)) pplier declarations, and /or analytical test data. tentional ingredient in the semiconductor device a asson to believe that the unavoidable impurity con- ss. You can access the UL iQTM family of database horide (PVC) plastic. "Window envelopes" used to tances restricted by RoHS in Microchip Technolog as of the date listed in this form. Microchip Technolog as of the date listed in Material Safety Data Sheets p not have been provided by subcontract assembler anticipated significant toxic metals components. I e finished parts. th respect to the information provided in this declar need in Microchip's standard terms and conditions clarations and shall not be liable for any damages ation in Material Content Declarations (MCD) or in	ALS: 100.000 (08 June 2011) and (08 June 2011) and (08 June 2011) and (08 June 2011) and (08 June 2011) and (09 June 2011) and (09 June 2012) and	7.400 I 2015/863/EU Microchip Tech hemical subst eport at slip on the out emiconductor cannot guaran terial suppliers. Info not include tr ive, limited pro provided in Mi consequential	1,000,000 31 March inology ance, if any, er box and devices in tee the supplier prination is ace levels of induct crochip's or	0.13		7440-21-3 Total Chip (Die) 2 7440-21-3 Total Wire Bond 1 7440-57-5 Total Wire Bond 2 7440-57-5 Total Plating on external Icotal Plating on external Icotal	% of Total Weight 100.00 100.00 % of Total Weight 100.00 100.00 100.00 % of Total Weight 100.00 % of Total Weight	3.81 1.70 0.65 0.15 12.76

100.00